

Notes:

1. All dimensions are in millimeters (inches).

Tolerance is ±0.25(0.01") unless otherwise noted.
Specifications are subject to change without notice.
The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAK4167 APPROVED: WYNEC

REV NO: V.2 **CHECKED:** Allen Liu DATE: APR/27/2010 DRAWN: Y.F.Lv



Erp	Color	Part No.	Luminous Flux (Im) @ 700mA [1]			Typical Luminous Flux (Im) [1]	
			Code.	Min.	Max.	Тур.	
1201200318	Cool White (InGaN)	AADG18080QR412S/3-C1	C2	120	140		
			C3	140	160	100	
			C4	160	180	- 160 -	
			C5	180	210		
1201200326	Neutral White (InGaN)	AADG18080QR412S/3-N1	C1	100	120	- 140	
			C2	120	140		
			C3	140	160		
			C4	160	180		
1201200328	Warm White (InGaN)	AADG18080QR412S/3-W2	C1	100	120	- 110	
			C2	120	140		
			C3	140	160	140 	
			C4	160	180		

Note:

1. Minimum luminous flux performance guaranteed within published operating conditions. Kingbright maintains tolerance of +/-15% on flux.

Optical Characteristics at 700mA Ambient Temperature, T_a = 25°C

Color		Correlated Color Temperature CCT	Typical Viewing Angle [1] (degrees)	
	Min.	Тур.	Max.	201/2
Cool White	5310K	6000K	7040K	100°
Neutral White	3710K	4500K	5310K	100°
Warm White	2580K	3000K	3710K	100°

Note:

1. Viewing angle is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.

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Electrical Characteristics at 700mA Ambient Temperature, T_a = 25°C

Part No.	Forward Voltage V _f [1] (V)			Typical Temperature Coefficient of Forward Voltage [2] (mV/°C)	Typical Thermal Resistance (°C/W) R _{th i-slug}	
	Min.	Тур.	Max.	$\Delta V_{f} / \Delta T$	• • th j-slug	
AADG18080QR412S/3-C1	-	4.6	5.2	-4.3	7	
AADG18080QR412S/3-N1	-	4.6	5.2	-4.3	7	
AADG18080QR412S/3-W2	-	4.6	5.2	-4.3	7	

Notes:

1.Kingbright maintains a tolerance of +/- 0.1V on forward voltage measurements. 2.Measured between 25 °C < TJ < 130 °C at IF = 700 mA.

Absolute Maximum Ratings

Parameter	Cool White / Neutral White / Warm White				
DC Forward Current (mA) [1]	700				
Peak Pusled Forward Current (mA)	1000				
Average Forward Current (mA)	700				
Reverse Voltage (V)	5				
ESD Sensitivity	8000V HBM				
LED Junction Temperature (°C)	130				
Operation Temperature (°C)	-40 to+100				
Storage Temperature (°C)	-40 to+110				
Soldering Temperature (°C)	260 For 5 Seconds				

Notes:

1. Proper current derating must be observed to maintain junction temperature below the maximum.

Moisture Sensitivity

AADG18080 LEDs are packaged in airtight and moisture-resistant bags to prevent moisture absorption which may lead to catastrophic failure in reflow soldering process. Kingbright recommends that the devices must be baked before soldering if they are removed from the original package, and are exposed to environmental conditions for longer than the durations (unit: days) defined in the table below. Recommended baking conditions are 24 hours at 80°C.

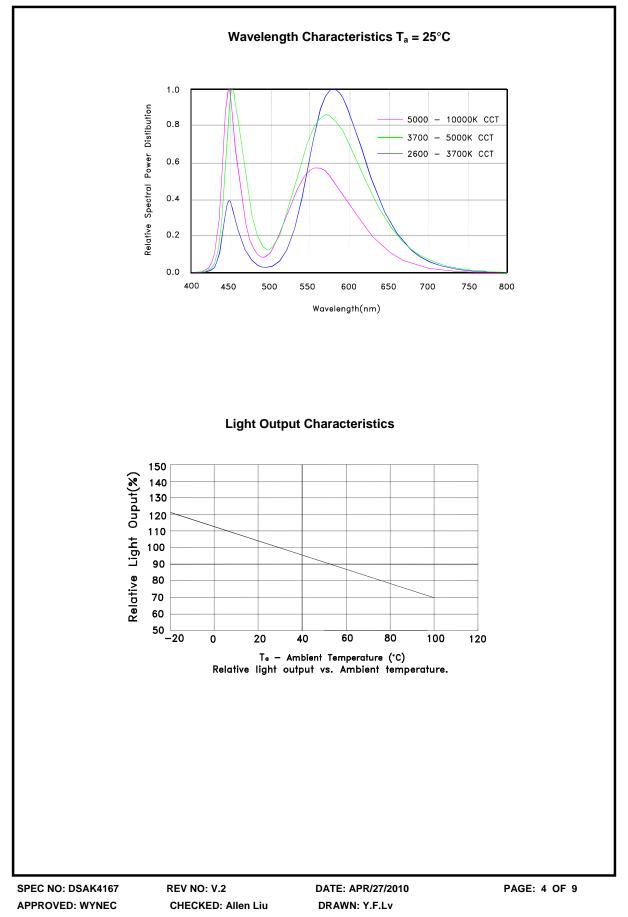
Temperature	Maximum Percent Relative Humidity							
	30%	40%	50%	60%	70%	80%	90%	
30°C	9	5	4	3	1	1	1	
25°C	12	7	5	4	2	1	1	
20°C	17	9	7	6	2	2	1	

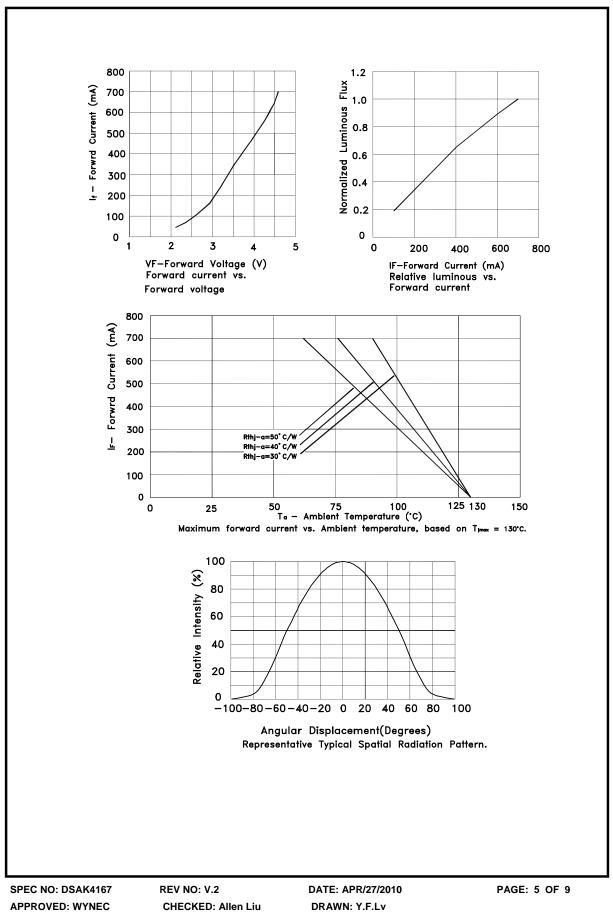
Storage Conditions

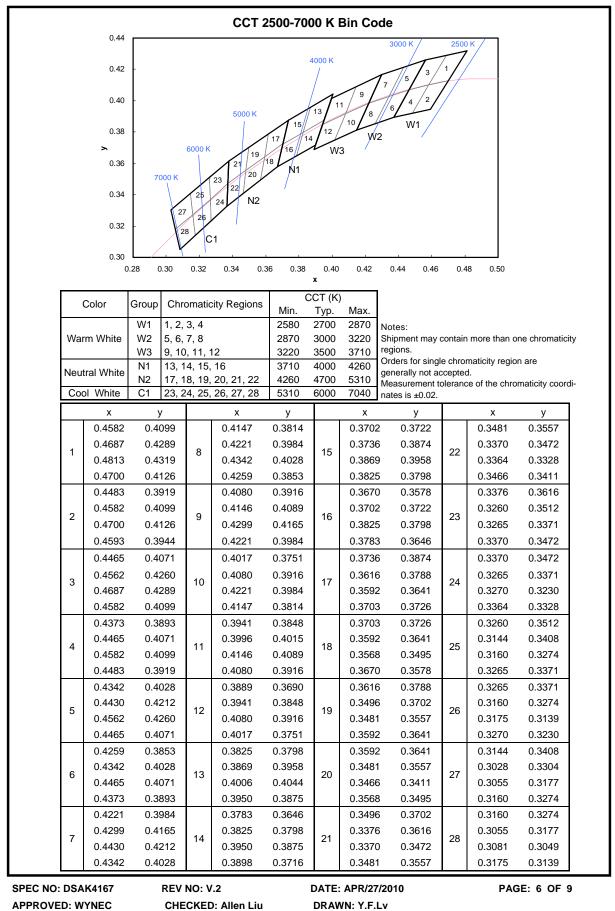
After being removed from the original sealed package, AADG18080 LEDs should be stored at a temperature of 25 °C with a relative humidity lower than 10%. Under such conditions, storage duration is excluded from the exposure duration as defined in the Moisture Sensitivity section.

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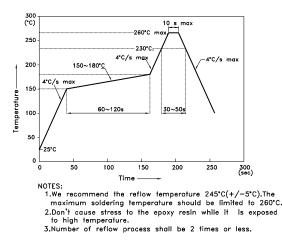






Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



Heat Generation:

1. Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board ,as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.

2.Please determine the operating current with consideration of the ambient temperature local to the LED and refer to the plot of Permissible Forward current vs. Ambient temperature on CHARACTERISTICS in this specification. Please also take measures to remove heat from the area near the LED to improve the operational characteristics on the LED.

3.The equation ① indicates correlation between T_j and T_a and the equation ② indicates correlation between T_j and T_s

Tj = Ta + Rthj-a *W ①

Tj = Ts + Rthj-s *W 2

Tj = dice junction temperature: $^\circ\!\mathrm{C}$

Ta = ambient temperature:°C

Ts = solder point temperature:°C

Rthj-a = heat resistance from dice junction temperature to ambient temperature : $^\circ\!\!C$ /W

Rthj-s = heat resistance from dice junction temperature to Ts measuring point : $^{\circ}C$ /W

W = inputting power (IFx VF) : W

